

### REMARKS

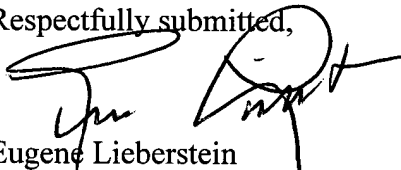
This Preliminary Amendment is being filed concurrently with the filing of the above-identified new patent application to amend the title.

The current title, METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES, is being amended to read as follows:

--METHOD OF MANUFACTURING SEMICONDUCTOR PACKAGES AND A CLAMPING DEVICE FOR MANUFACTURING A SEMICONDUCTOR PACKAGE--.

Applicant respectfully submits that no new matter is being added by way of the Preliminary Amendment and respectfully requests entry thereof.

Respectfully submitted,



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### MAILING CERTIFICATE

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as Express Mail in an envelope addressed: Commissioner for Patents, P.O. Box 1450, Arlington, VA 22313-1450, Mail Stop Patent Applications on April 20, 2004.



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Date: April 20, 2004